- Functionally Equivalent to AMD's AM29823 and AM29824
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Outputs Have Undershoot-Protection Circuitry
- Power-Up High-Impedance State
- Buffered Control Inputs to Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

description

These 9-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers, parity bus interfacing, and working registers.

With the clock-enable ($\overline{\text{CLKEN}}$) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock (CLK) input. Taking $\overline{\text{CLKEN}}$ high disables the clock buffer, latching the outputs. The SN54AS823A and SN74AS823A have noninverting data (D) inputs and the SN74AS824A has inverting ($\overline{\text{D}}$) inputs. Taking the clear ($\overline{\text{CLR}}$) input low causes the nine Q outputs to go low independently of the clock.

A buffered output-enable (\overline{OE}) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or the highimpedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

 \overline{OE} does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AS823A is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74AS823A and SN74AS824A are characterized for operation from 0°C to 70°C.

SN54AS823A JT PACKAGE
SN74AS823A DW OR NT PACKAGE
(TOP VIEW)

OE [1	24] v _{cc}
1D [2] 1Q
2D [3	22	2Q
3D [4	21] 3Q
4D [5	20] 4Q
5D [6	19] 5Q
6D [7	18] 6Q
7D [8	17]7Q
8D [9	16] 8Q
9D [9Q
CLR [11	14	CLKEN
GND [12	13] CLK

SN54AS823A . . . FK PACKAGE (TOP VIEW)



SN74AS824A . . . DW OR NT PACKAGE (TOP VIEW)

OE [1 U	24	V _{CC}
1D [2	23	1Q
2D [3	22	2Q
3D [4	21	3Q
4D [5	20	4Q
5D [6	19	5Q
6D [7	18	6Q
	8	17	7Q
8D [9	16	8Q
9D [10	15	9Q
CLR [11	14	CLKEN
GND [12	13	CLK

NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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Function Tables

SN54AS823A, SN74AS823A (each flip-flop)

			<u> </u>		
	OUTPUT				
OE	CLR	CLKEN	CLK	D	Q
L	L	Х	Х	Х	L
L	н	L	\uparrow	Н	Н
L	Н	L	\uparrow	L	L
L	Н	Н	Х	Х	Q ₀
н	Х	Х	Х	Х	Z

SN74AS824A (each flip-flop)

	(each hip-hop)										
	INPUTS										
OE	CLR	CLKEN	CLK	D	Q						
L	L	Х	Х	Х	L						
L	Н	L	\uparrow	Н	L						
L	Н	L	\uparrow	L	Н						
L	Н	Н	Х	Х	Q ₀						
н	Х	Х	Х	Х	Z						

logic symbols[†]



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



logic diagrams (positive logic)





Pin numbers shown are for the DW, JT, and NT packages.

To Eight Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54AS823A –55°C	C to 125°C
SN74AS823A, SN74AS824A	°C to 70°C
Storage temperature range	C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN	SN54AS823A			SN74AS823A SN74AS824A			
			MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V		
VIL	Low-level input voltage			0.8			0.8	V		
ЮН	High-level output current			-24			-24	mA		
IOL	Low-level output current			32			48	mA		
<u>۰</u> *		CLR low	7.5			6.5				
t _w *	Pulse duration	CLK high or low	9.5			8			ns	
		CLR high	8			8				
t _{su} *	Setup time before CLK [↑]	Data	7			6			ns	
		CLKEN high or low	8.5			7.5				
t _h *	Hold time after CLK^\uparrow	CLKEN low	0			0			ns	
ТА	Operating free-air temperature		-55		125	0		70	°C	

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



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PARAMETER		ARAMETER TEST CONDITIONS		SN	54AS82	3A	SN7 SN7	UNIT			
				MIN	TYP [†]	MAX	MIN	түр†	MAX		
VIK		V _{CC} = 4.5 V,	lı = -18 mA			-1.2			-1.2	V	
		V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2				
Vон			I _{OH} = -15 mA	2.4	3.2		2.4	3.2		V	
		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				
			I _{OL} = 32 mA		0.3	0.5				V	
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA					0.35	0.5	v	
IOZH		V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ	
I _{OZL}		V _{CC} = 5.5 V,	V _I = 0.4 V			-50			-50	μΑ	
lj –		V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
IIН		V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μA mA	
۱ _{IL}		V _{CC} = 5.5 V,	VI = 0.4 V			-0.5			-0.5		
lo‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA	
			Outputs high		49	80		49	80		
	SN54AS823A, SN74AS823A	V _{CC} = 5.5 V	Outputs low		61	100		61	100		
			Outputs disabled		64	103		64	103	mA	
ICC			Outputs high		49	80		49	80	mA	
	SN74AS824A	V _{CC} = 5.5 V	Outputs low		61	100		61	100		
			Outputs disabled		64	103		64	103		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	S823A	SN74A SN74A		
			MIN	MAX	MIN	MAX	
^t PLH	CLK	Am. 0	3.5	9	3.5	7.5	ns
t _{PHL}		Any Q	3.5	14	3.5	13	115
^t PHL	CLR	Any Q	3.5	16.5	3.5	15.5	ns
^t PZH	OE	A	4	12	4	11	
^t PZL	UE	Any Q	4	13	4	12	ns
^t PHZ	OE	Any O	1	10	1	8	ns
^t PLZ	UE	Any Q	1	10	1.5	8	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
5962-8952501LA	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8952501LA SNJ54AS823AJT	Samples
SNJ54AS823AJT	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8952501LA SNJ54AS823AJT	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



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